Amendments to the Specification

Please amend the specification as follows:

Please replace the paragraph bridging pages 2 and 3 with the following to correct a typographical error at the end of the paragraph:

Further, an adhesive composition capable of being used in hot-melt condition comprising (a) ethylene-glycidyl (meth)acrylate copolymer as a first polyethylene polymer, (b) ethylene-alkyl (meth)acrylate copolymer as a second polyethylene polymer, and (c) rosin having carboxyl group in the molecule, wherein cross-linking structure is formed between ethylene units in above-mentioned copolymers is also known (see Japanese Unexamined Patent Publication (Kokai) No. 10-316955). The cross-linking structure can be formed by irradiating electron beam to the mixture containing above-mentioned components (a) to (c). With this composition, problems associated with conventional reactive (curing) hot-melt adhesive such as slow cross-linking reaction, gradual deterioration of adhesive strength due to generation of reaction by-product, gelation during heating, etc., can be overcome. It is also advantageous in that it can be formed into film-like adhesive without using solvent.
~~125%~~

Please replace the paragraph on page 8 starting at line 23 and ending on line 33 with the following to correct a typographical error:

Ethylene-glycidyl (meth)acrylate copolymer can be prepared, for example, by using a monomer mixture containing (i) glycidyl (meth)acrylate monomer and (ii) ethylene monomer as starting material, and by ~~porimerization~~ polymerization under a predetermined condition. In addition to these monomers, monomers such as propylene, alkyl (meth)acrylate, vinyl acetate may be used as a third monomer as long as the operative effect of the present invention is not adversely affected. In such a case, the minimum carbon number of alkyl group in the alkyl (meth)acrylate is 1 and the maximum is 8.

Please replace the paragraph on page 11 starting at line 7 and ending on line 29 with the following to correct a typographical error:

The ethylene-α-olefin copolymer used as a third component, not only provides the above described operative effect derived from the ethylene structure to the adhesive composition, but also effectively lowers hygroscopicity, dielectric constant and dielectric loss tangent further than the ethylene glycidyl (meth)acrylate copolymer. ~~Theethylene-α-olefin~~ The ethylene-α-olefin copolymer also gives high initial adhesive strength to the adhesive composition even when it is in the form of thin film or film of 80 μm or less in thickness. High adhesive strength in the form of thin film or the like may be attributed to the α-olefin unit of this copolymer, because α-olefin typically has low glass transition temperature (Tg), and low crystallinity, and thus is elastomeric at ordinary temperature. When this copolymer is dispersed somewhat unevenly in the adhesive composition, high adhesive strength is thought to be developed in a mechanism similar to toughening effect of rubber dispersion phase in a heat-curable resin. In the ethylene-α-olefin copolymer, the ethylene unit together with the dispersed α-olefin unit is thought to be capable of exhibiting the effect of increasing the interaction at the interface with the ethylene-glycidyl (meth)acrylate copolymer or with the low density polyethylene.

Please replace the paragraph on page 24 starting at line 32 and ending on line 33 with the following to correct a typographical error:

~~4-hydroxybenzophenon~~ 4-hydroxybenzophenone, (4HBP) manufactured by Tokyo Kasei Kogyo Co.